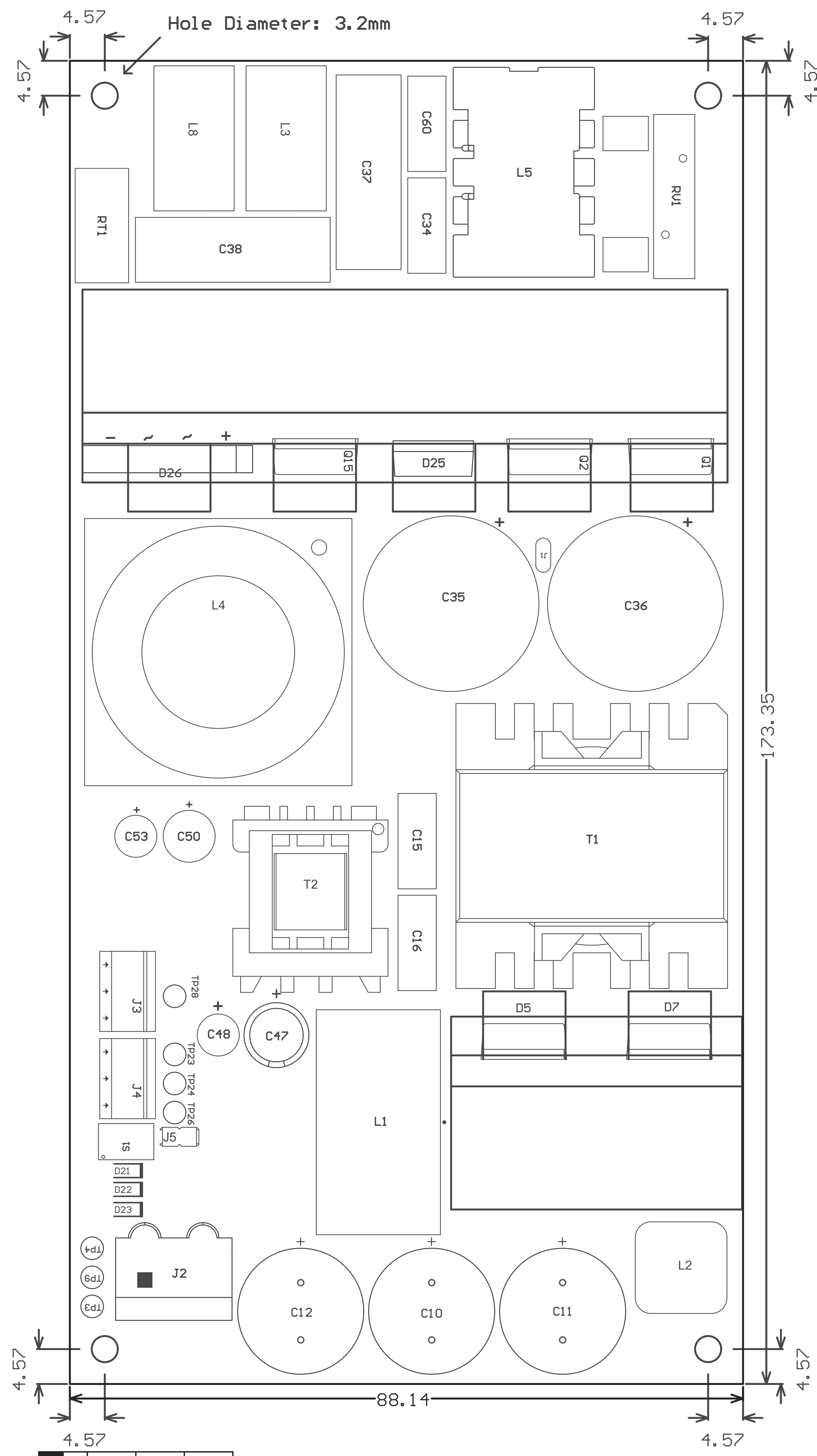


The Reference design PMP30183 Rev\_B has been built on PMP30183 Rev\_A PCB



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: [No Variations]

DESIGN INFORMATION	
MIN. TRACK WIDTH:	8 MIL
MIN. CLEARANCE:	0.2 mm
MIN. VIA PAD SIZE:	24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL PER IPC-D-275 CLASS 2 LEVEL C REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL	
MATERIAL:	
<input type="checkbox"/> FR-408	<input checked="" type="checkbox"/> FR-4 High Tg
<input type="checkbox"/> OTHER	
THICKNESS:	<input checked="" type="checkbox"/> 62 MIL (1.6mm) +/-10% <input type="checkbox"/> OTHER
TOLERANCE:	<input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2
	<input type="checkbox"/> OTHER +/-
BOW & TWIST:	<input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2
	<input type="checkbox"/> OTHER +/-
DRILLING:	
REFERENCE:	<input checked="" type="checkbox"/> AS SHOWN <input checked="" type="checkbox"/> NC_DRILL FILES
PTH MIN COPPER THICKNESS:	<input checked="" type="checkbox"/> 1MIL <input type="checkbox"/> OTHER
BOARD FINISH:	
SILKSCREEN:	<input checked="" type="checkbox"/> TOP <input checked="" type="checkbox"/> BOTTOM
SILKSCREEN COLOR:	<input checked="" type="checkbox"/> WHITE <input type="checkbox"/> OTHER
SOLDER RESIST COLOR:	
	<input checked="" type="checkbox"/> GREEN <input type="checkbox"/> BLUE <input type="checkbox"/> OTHER
SURFACE FINISH:	
	<input checked="" type="checkbox"/> IMMERSION GOLD (ENIG) <input type="checkbox"/> ENEPIG
	<input type="checkbox"/> IMM. TIN/SILVER OR EQUIV <input type="checkbox"/> OTHER
ARRAY/PANEL:	
	<input type="checkbox"/> CUT AND TRIM PER MECH LAYER 1
	<input type="checkbox"/> N.C. ROUTE <input checked="" type="checkbox"/> V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:	
	<input checked="" type="checkbox"/> ANSI IPC-A-600F CLASS -> <input type="checkbox"/> 1 <input checked="" type="checkbox"/> 2 <input type="checkbox"/> 3
	<input checked="" type="checkbox"/> UL 94V-0 <input checked="" type="checkbox"/> RoHS <input type="checkbox"/> OTHER PER ORDER
ADDITIONAL REQUIREMENTS:	
MICROSECTION:	<input type="checkbox"/> YES
BARE BOARD ELEC. TEST:	<input type="checkbox"/> NONE <input checked="" type="checkbox"/> REQUIRED <input type="checkbox"/> PER ORDER
MANUFACTURER'S UL:	<input type="checkbox"/> RAIL <input type="checkbox"/> METAL <input checked="" type="checkbox"/> SILK

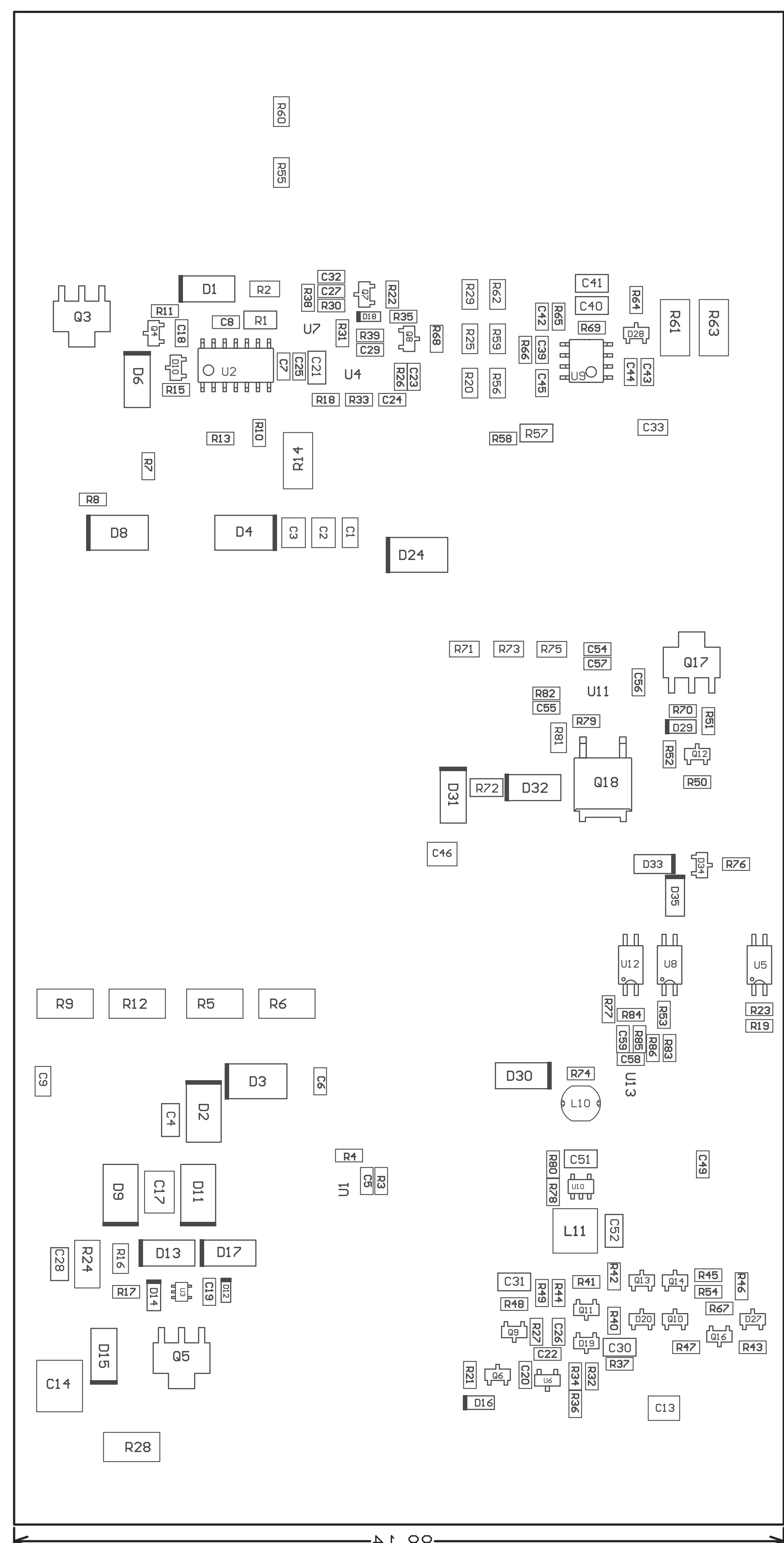


PROJECT TITLE:  
Universal line, 200Wavg, 840Wpeak Audio PSU

DESIGNED FOR:  
Public Release

FILE NAME:  
PMP30183 Rev\_A PCB.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: PMP30183	REV: A	SUN REV: Not In VersionControl	Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.	ENGINEER: R. Scibilia	LAYOUT BY: R. Scibilia
PLOT NAME = Top Layer Assembly Drawing	TID #: .TID	GENERATED : 11/6/2017 10:58:37 AM	TEXAS INSTRUMENTS		SCALE: 1.00	ALTIUM DESIGNER VERSION: 17.1.5.472



**DESIGN INFORMATION**

REGISTRATION TOLERANCES: METAL +/- 0.125 MIL HOLES +/- 0.125 MIL  
 PER IPC-D-275 CLASS 2 LEVEL C  
 MINIMUM ANNULAR RING 0.025mm (2MIL) EXTERNAL  
 MIN. VIA PAD SIZE: 0.25 MIL  
 MIN. CLEARANCE: 0.25 mm  
 MIN. TRACK WIDTH: 8 MIL

**MATERIAL:**  
 FR-408  FR-4 High Tg  OTHER  
 THICKNESS: 62 MIL (1.6mm) +/- 10%  OTHER

**TOLERANCE:**  
 ANSI IPC-6012 TYPE 3 CLASS 2  
 OTHER +/-

**BOW & TWIST:**  
 ANSI IPC-6012 TYPE 3 CLASS 2  
 OTHER +/-

**DRILLING:**  
 REFERENCE:  AS SHOWN  NC DRILL FILES  
 PTH MIN COPPER THICKNESS:  1MIL  OTHER

**BOARD FINISH:**  
 SILKSCREEN:  TOP  BOTTOM  
 SILKSCREEN COLOR:  WHITE  OTHER  
 SOLDER RESIST COLOR:  GREEN  BLUE  OTHER

**SURFACE FINISH:**  
 IMMERSION GOLD (ENIG)  ENIG  
 IMM. TIN/SILVER OR EQUIV  OTHER

**ARRAY PANEL:**  
 CUT AND TRIM PER MECH LAYER 1  
 N.C. ROUTE  V. SCORE

**CERTIFICATION:** MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:  
 ANSI IPC-A-600F CLASS 2  1  2  3  
 UL 94V-0  RoHS  OTHER PER ORDER

**ADDITIONAL REQUIREMENTS:**  
 MICROSECTION:  YES  
 BARE BOARD ELEC. TEST:  NONE  REQUIRED  PER ORDER  
 MANUFACTURER'S UL:  RAL  METAL  SILK

**TEXAS INSTRUMENTS**

PROJECT TITLE: Universal Line, 200Wavg, 840Wpeak Audio PSU  
 DESIGNED FOR: Public Release  
 FILE NAME: PMP30183 Rev\_A PCB.pcbDoc

ENGINEER: R. Scidilia  
 LAYOUT BY: R. Scidilia  
 SCALE: 1:00  
 ALTM DESIGNER VERSION: 12.1.2.422

completely visible and test your design implementation to confirm the specification for your application. You should implement the design in a production environment. You should implement the design in a production environment. You should implement the design in a production environment.

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP30183	REV: A	SUN REV: Not In VersionControl
PLOT NAME = Bottom Layer Assembly Drawing	TID #: .TID	GENERATED : 11/6/2017 10:58:38 AM	TEXAS INSTRUMENTS

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